

Product Change Notification / LIAL-07JNOW904

Date:

12-Dec-2022

Product Category:

Motor Drivers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4952 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MCP8025xx and MCP8026xx device families available in 40L QFN (5x5x0.9mm) package assembled at MMT assembly site.

Affected CPNs:

LIAL-07JNOW904_Affected_CPN_12122022.pdf LIAL-07JNOW904_Affected_CPN_12122022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MCP8025xx and MCP8026xx device families available in 40L QFN (5x5x0.9mm) package assembled at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (Branch) / (MMT)			
Wire Material	Au	Au	CuPdAu			
Die Attach Material	3280	3280	3280			
Molding Compound Material	G700LTD	G700LTD	G700LTD			
Lead-Frame Material	C194	C194	C194			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status: In Progress

Estimated First Ship Date: January 7, 2023 (date code: 2302)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2022			→	December 2022				January 2023						
Workweek	06	07	08	09		49	50	51	52	53	01	02	03	04	05
Initial PCN Issue Date		х													
Qual Report Availability								х							
Final PCN Issue Date								х							
Estimated Implementation Date												х			

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 7, 2022: Issued initial notification. December 12, 2022: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on January 7, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-07JNOW904-Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-07JNOW904 - CCB 4952 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected MCP8025xx and MCP8026xx device families available in 40L QFN (5x5x0.9mm) package assembled at MMT assembly site.

Affected Catalog Part Numbers (CPN)

MCP8025-115E/MP MCP8026-115E/MP MCP8026-115E/MPB3 MCP8025A-115E/MP MCP8025T-115H/MP MCP8026T-115H/MP MCP8025AT-115H/MP MCP8025A-115H/MP MCP8025A-115H/MP MCP8025T-115E/MP MCP8026T-115E/MP MCP8026T-115E/MPB3